

## ECOFLOOR F - insulation board



ECOFLOOR F under tile thermal backing board is used to provide thermal decoupling between the base floor and the tile floor coverings.

This minimises the the downward heat loss and facilitates a faster warm up time, saving the home owner on running costs and providing a more pleasant warming of the floor.

In small application zones, where the greater floor area represents a comparatively large heat sink, thermal backing board reduces the heat waste going into the base floor and ensures the floor heats up to a warmer and more pleasant temperature quicker.

In addition, on multilevel builds, the thermal backing board helps to reduce accoustic coupling to the lower building level.

The board comprises an XPS foam core with a cementitious fiber reinforced top and bottom skin and offers a high level of water resistance, thermal insulation and compressive strength. It is available in 6mm and 10mm thick sheets which are 1200mm X 600mm light weight, easy to install sheets.

Characteristic	Standard	Value	Detail
Fire resistance	DIN EN 13501 DIN 4102	E B1	
Thermal conductivity	DIN EN 13164	0.029Wm <sup>-1</sup> K <sup>-1</sup>	
Compression strength	DIN EN 826	450kPa	@10% of deformation.
Tensile strength	DIN EN 1607	800 kPa	Vertical to board surface
Long term absorptivity	DIN 12087	<1.5%	

Product	Thickness	Dimension (mm)	R Value (m kW <sup>-1</sup> )
ECOFLOOR Board F6	6mm	1200 X 600	0.16
ECOFLOOR Board F10	10mm	1200 X 600	0.29